

Title (en)

METHOD FOR THE PRODUCTION OF A CHIP-CARD TYPE PORTABLE STORAGE MEDIUM

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES EC-KARTENARTIGEN TRAGBAREN SPEICHERTRÄGERS

Title (fr)

PROCEDE DE FABRICATION DE SUPPORT DE MEMORISATION PORTABLE DE TYPE CARTE A PUCE

Publication

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Application

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Priority

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Abstract (en)

[origin: FR2789505A1] The invention relates to a method for the production of chip-card type portable storage media comprising flush contact pads on a substrate in addition to an integrated circuit chip accommodated in a cavity formed in said media and provided with contact studs that are electrically connected to the flush contact pads. The inventive method includes a stage in which the contact pads are produced and another stage in which the substrate elements are installed and the integrated circuit chip is placed into the cavity. According to the invention, during the stage in which the contact pads are produced, conductive material is imprinted on the first surface of an adhesive dielectric film (100). In the installation stage, the second surface of the adhesive dielectric film (100) is fixed in said cavity. The invention can be used in the production of chip card modules and chip cards.

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